



(19)

JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: 2003031937 A

(43) Date of publication of application: 31.01.03

(51) Int. Cl.

H05K 3/34

(21) Application number: 2001218439

(22) Date of filing: 18.07.01

(71) Applicant: SONY CORP

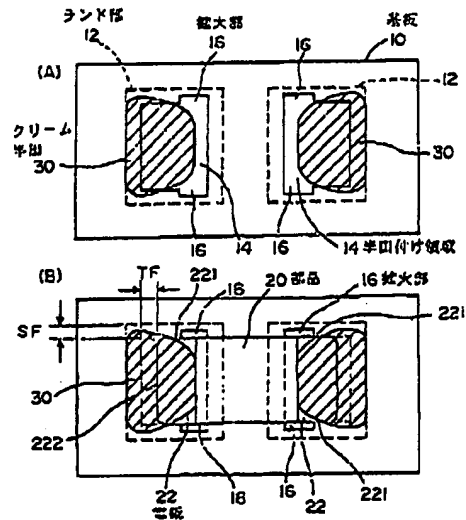
(72) Inventor: MORIUCHI NOBUKIMI

(54) SOLDERING LAND STRUCTURE FOR SURFACE MOUNTING TYPE COMPONENT

(57) Abstract:

PROBLEM TO BE SOLVED: To suppress unstable behaviors of mounted components in a reflow step to ensure a stable mounting quality and easily realize a narrow-gap mounting.

SOLUTION: A pair of lands 12 are provided with a spacing, corresponding to electrodes 22 at both ends of a component 20 on a wiring board 10. A solder resist covers the peripheral edge 121 of the land 12 and the surface of the board 10 adjacent thereto, to thereby form solder regions 14 of specified surface areas for soldering the electrodes 22 on the surface of each land 12. Deviation-suppressing expanded portions 16, for locally expanding the area of the solder regions 14, are formed on side fillets SF side edges of the solder regions 14, facing mutually opposed sides 221 of the electrodes 22 in the width direction of the electrode 22.



COPYRIGHT: (C)2003,JPO